APPLICAI	BLE STAN	DARD									
OPERATING TEMPERATURE RANGE			-40 °C TO +85 °C(N	OTE1)/3	STORAGE TEMPERA	TURE RANG	SE -10 °(	C TO +60 °C	(NOTI	E2)	
RATING	OPERATING HUMIDITY RANGE		40 % TO 80 %(NOTE3)		STORAGE HUMIDITY		40 % TO 70 % (NOTE2)				
	VOLTAGE	,,,,	10.050.1/		UL · CSA	VOLTAGE	10001			<i>-,</i>	
	CURRENT		2A		RATING	CURRENT	+	2A			
			SPEC	IFICATI		CONNENT					
IT	EM		TEST METHOD			RE	QUIREMEN	ITS	QT	AT	
CONSTR											
		VISUALLY AND BY MEASURING INSTRUMENT.			ACCO	ACCORDING TO DRAWING.				×	
MARKING		CONFIRMED VISUALLY.								×	
	C CHARA				laa -						
		100 mA (DC OR 1000 Hz).				30 mΩ MAX.				_	
INSULATION RESISTANCE						1000 MΩ MIN.				_	
VOLTAGE PROOF		650 V AC FOR 1 min.			NO FL	NO FLASHOVER OR BREAKDOWN.				-	
	IICAL CHA										
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.			② NO	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				-	
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			② NO	(Î) NO ELECTRICAL DISCONTINUITY OF 1µs. (2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				-	
SHOCK		490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			② NO	NO ELECTRICAL DISCONTINUITY OF 1µs.     NO DAMAGE, CRACK OR LOOSENESS     OF PARTS.				-	
ENVIRON	MENTAL	CHARA	ACTERISTICS			174(10.					
DAMP HEAT (STEADY STATE)		EXPOSED AT 40±2 °C, 90 TO 95 %, 96 h.			2 INS 3 NO	<ol> <li>CONTACT RESISTANCE: 30 mΩ MAX.</li> <li>INSULATION RESISTANCE:500 MΩMIN.</li> <li>NO DAMAGE, CRACK OR LOOSENESS OF PARTS.</li> </ol>				_	
RAPID CHANGE OF TEMPERATURE		TEMPERATURE $-55 \rightarrow 5$ TO $35 \rightarrow 85 \rightarrow 5$ TO $35$ °C TIME $30 \rightarrow 10$ TO $15 \rightarrow 10 \rightarrow 15$ TO 3 min UNDER 5 CYCLES.			C ① CO in ② INS ③ NO	<ol> <li>CONTACT RESISTANCE: 30 mΩ MAX.</li> <li>INSULATION RESISTANCE: 1000MΩMIN.</li> <li>NO DAMAGE, CRACK OR LOOSENESS OF PARTS.</li> </ol>				-	
RESISTANCE TO SOLDERING HEAT		( )				NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.				_	
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE,230°C FOR IMMERSION DURATION,3 sec.				SOLDER SHALL COVER A MINIMUM OF 95% OF THE SURFACE BEING IMMERSED				_	
COUN	T DE				ESIGNED		CHECKED		_	DATE 14, 02, 26	
Z3A 1 REMARKS	<u>Ma</u> 1   DIS-H-008 EMARKS		.1-008540   MT. SAK		SAKIMURA		HK. UMEHARA  APPROVED KJ. KATAYOSE				
NOTE1:INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCE						, <sub>BD</sub>	CHECKED			01. 05  01. 05	
AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTE						RAGE					
NOTE3:NON-CONDENSING. Unless otherwise specified, refer to IEC 60512.						-	DESIGNED DRAWN	10. DENPOUYA	05.01.05		
·								IO. DENPOUYA	05.01.05		
Note QT:Qualification Test AT:Assurance Test X:Applicable Test					DRAWING NO. ELC4-080551-0			·U I			
	SPECIFICATION SHEET  HIROSE ELECTRIC CO., LTD.  COD				1	DE44	/ / /	١			
HS.				PA	ART NO.		OF 11-*	DP-2DSA (01	<b>A</b>	1/1	